

**REMOVAL METHOD OF SUPPORT PLATE AND PROCESSING METHOD OF
PLATE-SHAPED MEMBER**

ABSTRACT

A removal method of a support plate includes a curing step of irradiating with ultraviolet an adhesion layer that contains a curing material and bonds a support plate that allows the ultraviolet to be transmitted through the support plate to a plate-shaped member, from the support plate side to cure the curing material, a void forming step of forming a plurality of voids in a surface in contact with the support plate in the adhesion layer through irradiating the adhesion layer with a laser beam with such a wavelength as to be transmitted through the support plate from the support plate side, and a support plate removal step of separating the support plate from the adhesion layer with the surface in which the plurality of voids are formed being the border to remove the support plate from the adhesion layer bonding to the plate-shaped member.

[FIG. 7]